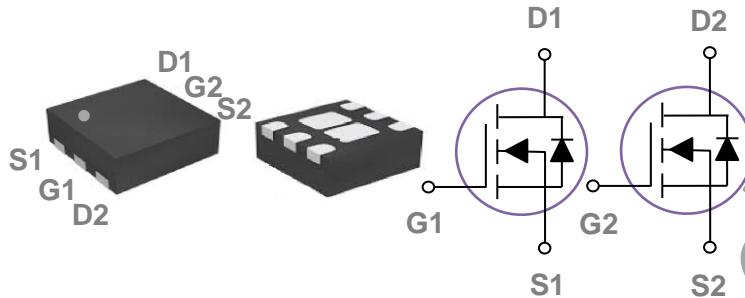


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### DFN2X2 Dual 2EP Pin Configuration



BVDSS	RDS(ON)	ID
30V	30mΩ	5.0A

### Features

- 30V, 5.0A, RDS(ON) = 30mΩ @ VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2nd SR

### Absolute Maximum Ratings Tc=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>A</sub> =25°C)	5.0	A
	Drain Current – Continuous (T <sub>A</sub> =70°C)	4.0	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	20	A
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> =25°C)	1.25	W
	Power Dissipation – Derate above 25°C	0.01	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	100	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_D=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $\text{I}_D=1\text{mA}$	---	0.02	---	$^\circ\text{C}$
$\text{I}_{\text{DS}}$	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=30\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$\text{V}_{\text{DS}}=24\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$ , $\text{V}_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>3</sup>	$\text{V}_{\text{GS}}=10\text{V}$ , $\text{I}_D=3\text{A}$	---	22	30	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}$ , $\text{I}_D=2\text{A}$	---	35	46	$\text{m}\Omega$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$ , $\text{I}_D = 250\mu\text{A}$	1.2	1.5	2.5	V
$\Delta \text{V}_{\text{GS(th)}}$	$\text{V}_{\text{GS(th)}}$ Temperature Coefficient		---	-3.2	---	$\text{mV}/^\circ\text{C}$
$\text{gfs}$	Forward Transconductance	$\text{V}_{\text{DS}}=10\text{V}$ , $\text{I}_D=3\text{A}$	---	4	---	S

**Dynamic and switching Characteristics**

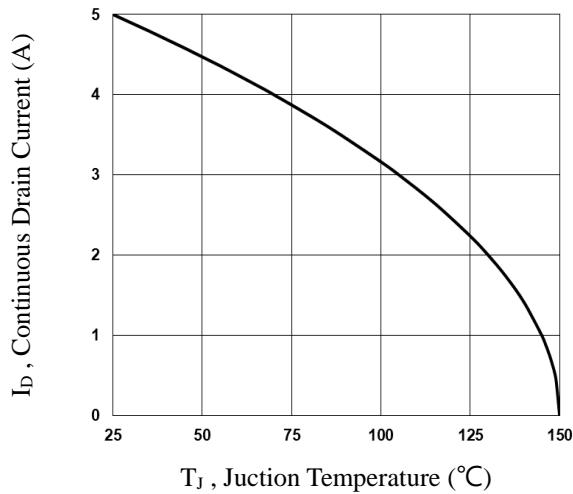
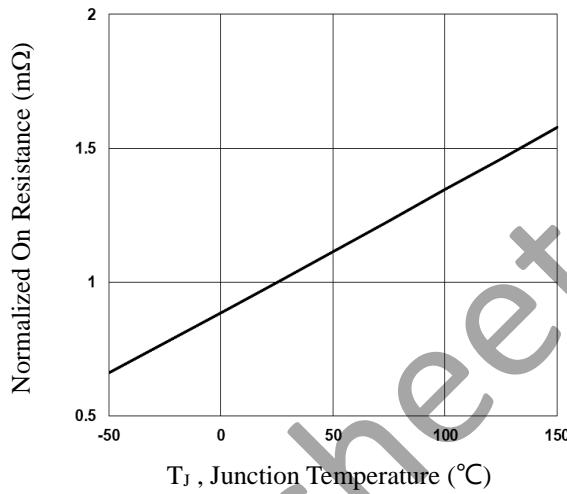
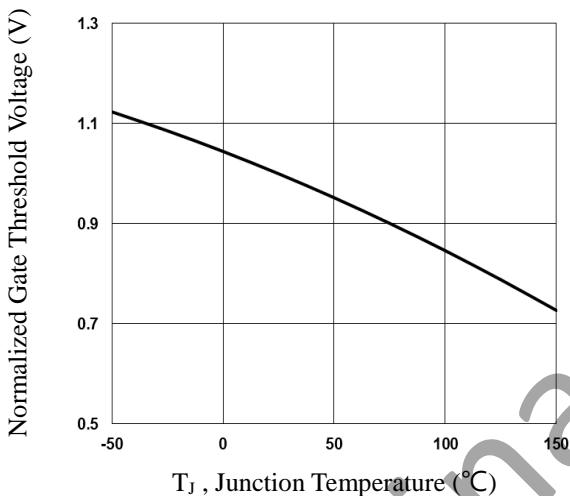
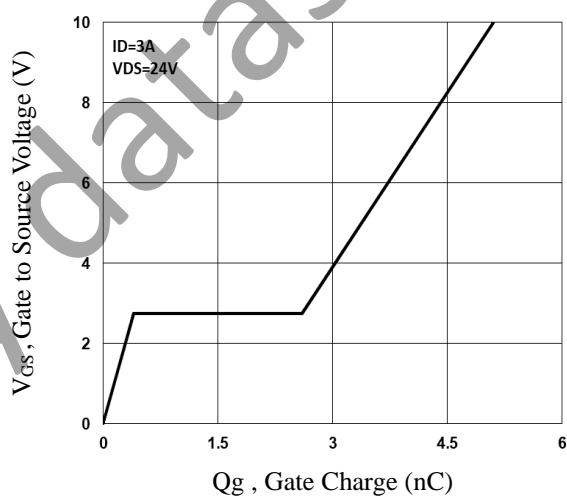
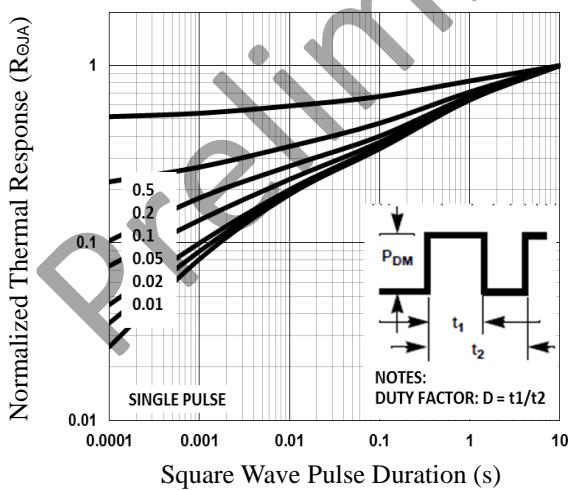
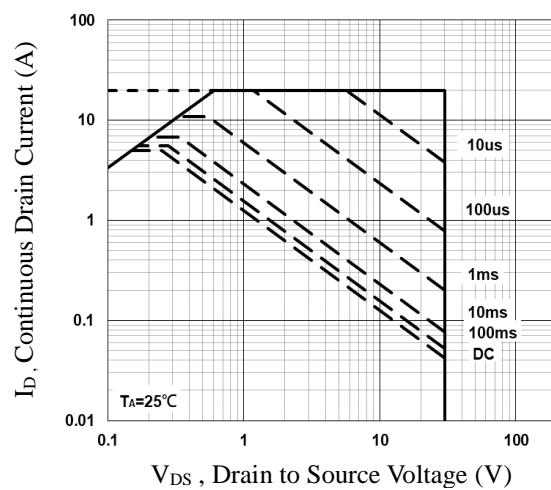
$\text{Q}_g$	Total Gate Charge <sup>2,3</sup>	$\text{V}_{\text{DS}}=24\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $\text{I}_D=3\text{A}$	---	5.1	10	nC
$\text{Q}_{\text{gs}}$	Gate-Source Charge <sup>2,3</sup>		---	0.4	1.0	
$\text{Q}_{\text{gd}}$	Gate-Drain Charge <sup>2,3</sup>		---	2.2	4.5	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time <sup>2,3</sup>	$\text{V}_{\text{DD}}=15\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $\text{R}_G=6\Omega$ $\text{I}_D=1\text{A}$	---	2.6	5	ns
$\text{T}_r$	Rise Time <sup>2,3</sup>		---	8.8	16	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time <sup>2,3</sup>		---	18.4	35	
$\text{T}_f$	Fall Time <sup>2,3</sup>		---	5.1	10	
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{DS}}=25\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $\text{F}=1\text{MHz}$	---	333	660	pF
$\text{C}_{\text{oss}}$	Output Capacitance		---	52	100	
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance		---	43	85	
$\text{R}_g$	Gate resistance	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{V}_{\text{DS}}=0\text{V}$ , $f=1\text{MHz}$	---	0.95	2	$\Omega$

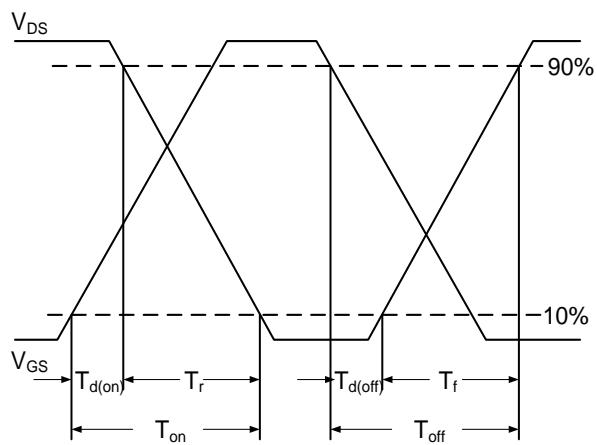
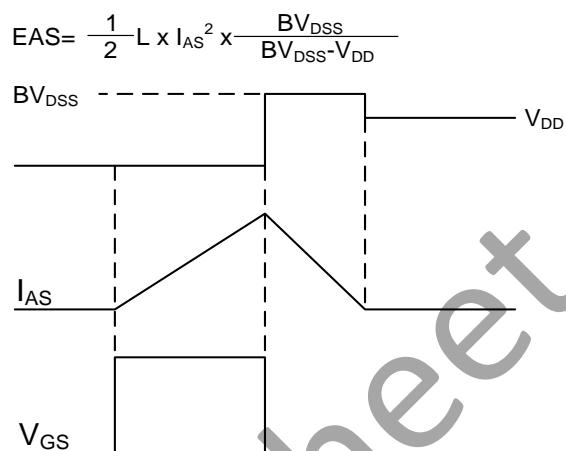
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{I}_s$	Continuous Source Current	$\text{V}_G=\text{V}_D=0\text{V}$ , Force Current	---	---	5	A
$\text{I}_{\text{SM}}$	Pulsed Source Current <sup>3</sup>		---	---	10	A
$\text{V}_{\text{SD}}$	Diode Forward Voltage <sup>3</sup>	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V

Note :

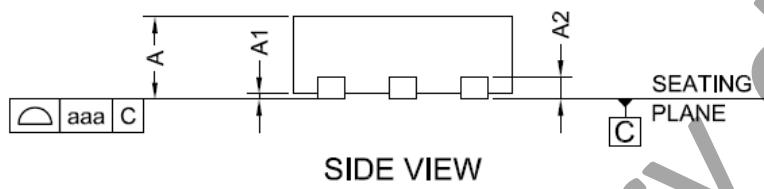
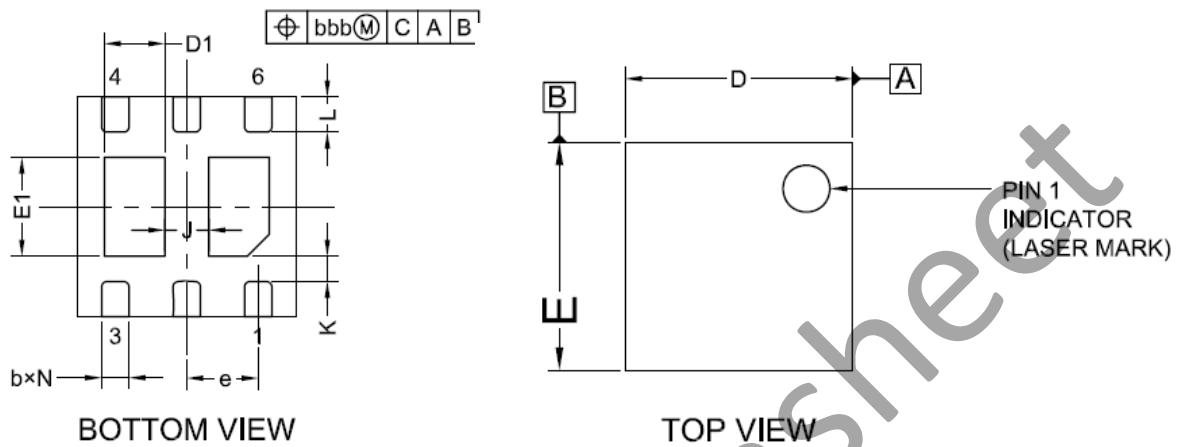
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs.  $T_J$** 

**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$** 

**Fig.3 Normalized  $V_{th}$  vs.  $T_J$** 

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Response**

**Fig.6 Maximum Safe Operation Area**


**Fig.7 Switching Time Waveform**

**Fig.8 EAS Waveform**

Preliminary datasheet

## DFN2X2 Dual 2EP PACKAGE INFORMATION



**COMMON DIMENSIONS**  
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	TYP	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2		0.203	
b	0.20	0.25	0.30
D	1.95	2.00	2.05
D1	0.50	0.55	0.60
E	1.95	2.00	2.05
E1	0.85	0.90	0.95
e		0.65BSC	
L	0.27	0.32	0.37
J		0.40BSC	
K		0.20MIN	
N		6	
aaa		0.08	
bbb		0.10	